MJ10000

Designer's™ Data Sheet

SWITCHMODE Series
NPN Silicon Power Darlington
Transistor

**20 AMPERE
NPN SILICON
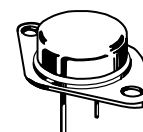POWER DARLINGTON
TRANSISTORS
350 VOLTS
175 WATTS**

The MJ10000 Darlington transistor is designed for high–voltage, high–speed, power switching in inductive circuits where fall time is critical. It is particularly suited for line operated switchmode applications such as:

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits

100°C Performance Specified for:
  Reversed Biased SOA with Inductive Loads
  Switching Times With Inductive Loads —
   210 ns Inductive Fall Time (Typ)
  Saturation Voltages
  Leakage Currents

≈ 100 ≈ 15

**CASE 1–07
TO–204AA
(TO–3)**

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V_{CEO}	350	Vdc
Collector–Emitter Voltage	V_{CEX}	400	Vdc
Collector–Emitter Voltage	V_{CEV}	450	Vdc
Emitter Base Voltage	V_{EB}	8	Vdc
Collector Current — Continuous — Peak (1)	I_C I_{CM}	20 30	Adc
Base Current — Continuous — Peak (1)	I_B I_{BM}	2.5 5	Adc
Total Power Dissipation @ T_C = 25°C @ T_C =100°C Derate above 25°C	P_D	175 100 1	Watts W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8″ from Case for 5 Seconds	T_L	275	°C

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

MOTOROLA

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS (2)					
Collector–Emitter Sustaining Voltage (Table 1) (I_C = 250 mA, I_B = 0, V_{clamp} = Rated V_{CEO}) MJ10000	$V_{CEO(sus)}$	350	—	—	Vdc
Collector–Emitter Sustaining Voltage (Table 1, Figure 12) I_C = 2 A, V_{clamp} = Rated V_{CEX}, T_C = 100°C MJ10000 I_C = 10 A, V_{clamp} = Rated V_{CEX}, T_C = 100°C MJ10000	$V_{CEX(sus)}$	 400 275	 — —	 — —	Vdc
Collector Cutoff Current (V_{CEV} = Rated Value, $V_{BE(off)}$ = 1.5 Vdc) (V_{CEV} = Rated Value, $V_{BE(off)}$ = 1.5 Vdc, T_C = 150°C)	I_{CEV}	 — —	 — —	 0.25 5	mAdc
Collector Cutoff Current (V_{CE} = Rated V_{CEV}, R_{BE} = 50 Ω, T_C = 100°C)	I_{CER}	—	—	5	mAdc
Emitter Cutoff Current (V_{EB} = 8 Vdc, I_C = 0)	I_{EBO}	—	—	150	mAdc
SECOND BREAKDOWN					
Second Breakdown Collector Current with base forward biased	$I_{S/b}$		See Figure 11		Adc
ON CHARACTERISTICS (2)					
DC Current Gain (I_C = 5 Adc, V_{CE} = 5 Vdc) (I_C = 10 Adc, V_{CE} = 5 Vdc)	h_{FE}	 50 40	 — —	 600 400	—
Collector–Emitter Saturation Voltage (I_C = 10 Adc, I_B = 400 mAdc) (I_C = 20 Adc, I_B = 1 Adc) (I_C = 10 Adc, I_B = 400 mAdc, T_C = 100°C)	$V_{CE(sat)}$	 — — —	 — — —	 1.9 3 2	Vdc
Base–Emitter Saturation Voltage (I_C = 10 Adc, I_B = 400 mAdc) (I_C = 10 Adc, I_B = 400 mAdc, T_C = 100°C)	$V_{BE(sat)}$	 — —	 — —	 2.5 2.5	Vdc
Diode Forward Voltage (1) (I_F = 10 Adc)	V_f	—	3	5	Vdc
DYNAMIC CHARACTERISTICS					
Small–Signal Current Gain (I_C = 1.0 Adc, V_{CE} = 10 Vdc, f_{test} = 1 MHz)	h_{fe}	10	—	—	—
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f_{test} = 100 kHz)	C_{ob}	100		325	pF
SWITCHING CHARACTERISTICS					
Resistive Load (Table 1)					
Delay Time (V_{CC} = 250 Vdc, I_C = 10 A, Rise Time I_{B1} = 400 mA, $V_{BE(off)}$ = 5 Vdc, t_p = 50 μs, Storage Time Duty Cycle ≤ 2%) Fall Time	t_d t_r t_s t_f	— — — —	0.12 0.20 1.5 1.1	0.2 0.6 3.5 2.4	μs μs μs μs
Inductive Load, Clamped (Table 1)					
Storage Time (I_C = 10 A(pk), V_{clamp} = Rated V_{CEX}, I_{B1} = 400 mA, Crossover Time $V_{BE(off)}$ = 5 Vdc, T_C = 100°C)	t_{sv} t_c	— —	3.5 1.5	5.5 3.7	μs μs
Storage Time (I_C = 10 A(pk), V_{clamp} = Rated V_{CEX}, I_{B1} = 400 mA, Crossover Time $V_{BE(off)}$ = 5 Vdc, T_C = 25°C)	t_{sv} t_c	— —	1.0 0.7	— —	μs μs

(1) The internal Collector–to–Emitter diode can eliminate the need for an external diode to clamp inductive loads.
     Tests have shown that the Forward Recovery Voltage (V_f) of this diode Is comparable to that of typical fast recovery rectifiers.
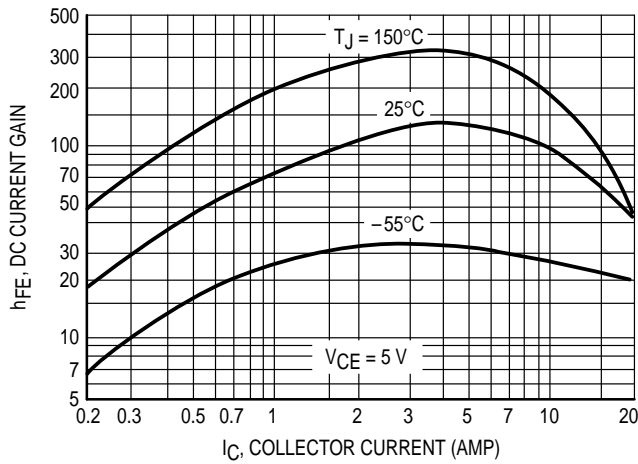(2) Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

DC CHARACTERISTICS

Figure 1. DC Current Gain
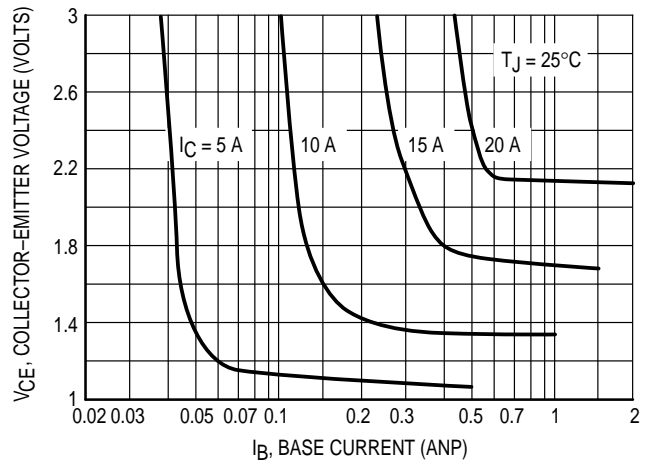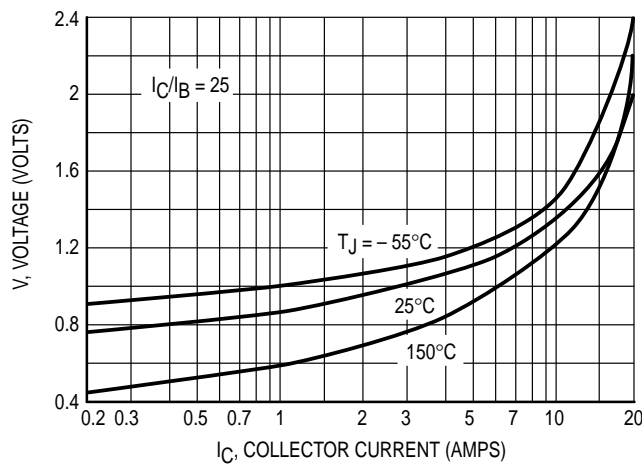

Figure 2. Collector Saturation Region

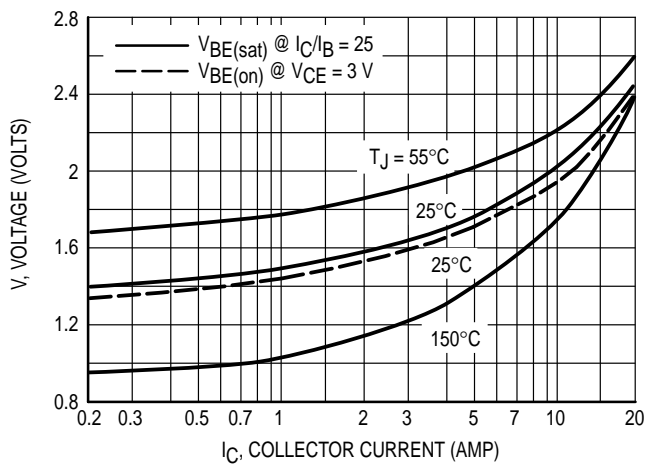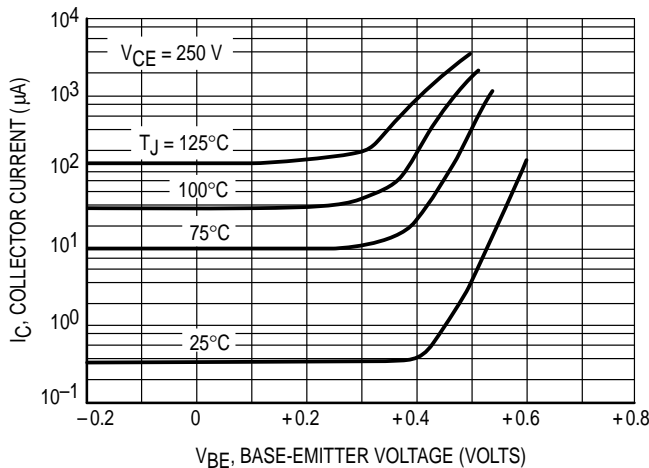**Figure 3. Collector Emitter Saturation Voltages**

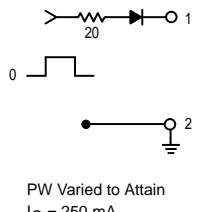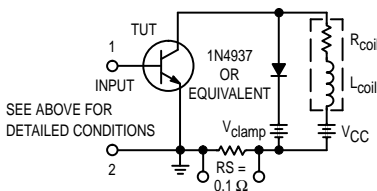**Figure 4. Base-Emitter Voltage**

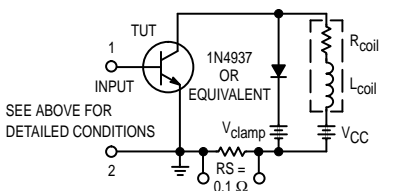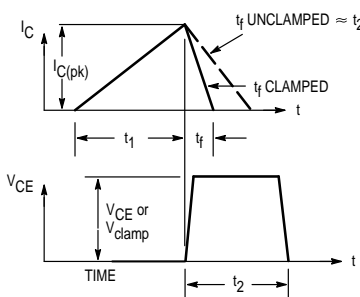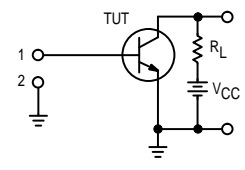**Figure 5. Collector Cutoff Region**
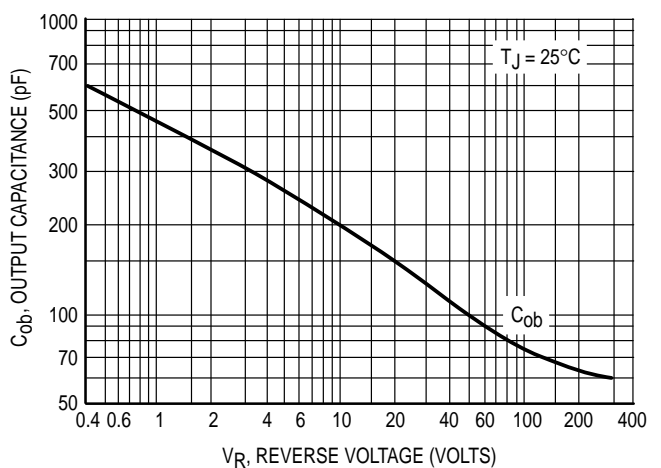
Figure 6. Output Capacitance

Table 1. Test Conditions for Dynamic Performance

|	$V_{CEO(sus)}$	$V_{CEX(sus)}$ AND INDUCTIVE SWITCHING	RESISTIVE SWITCHING
INPUT CONDITIONS	PW Varied to Attain I_C = 250 mA	**INDUCTIVE TEST CIRCUIT**	
CIRCUIT VALUES	L_{coil} = 10 mH, V_{CC} = 10 V R_{coil} = 0.7 Ω V_{clamp} = $V_{CEO(sus)}$	L_{coil} = 180 µH R_{coil} = 0.05 Ω V_{CC} = 20 V V_{clamp} = Rated V_{CEX} Value	V_{CC} = 250 V R_L = 25 Ω Pulse Width = 50 µs
TEST CIRCUITS	**INDUCTIVE TEST CIRCUIT**	**OUTPUT WAVEFORMS** t_1 Adjusted to Obtain I_C $$t_1 \approx \frac{L_{coil}(I_{Cpk})}{V_{CC}}$$ $$t_2 \approx \frac{L_{coil}(I_{Cpk})}{V_{Clamp}}$$ Test Equipment Scope — Tektronix 475 or Equivalent	**RESISTIVE TEST CIRCUIT**
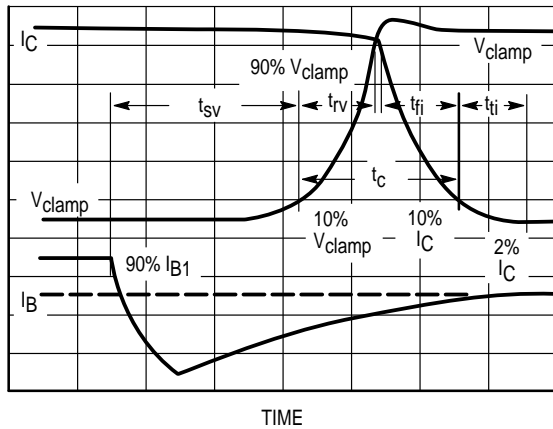
Figure 7. Inductive Switching Measurements

SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

t_{sv} = Voltage Storage Time, 90% I_{B1} to 10% V_{clamp}
t_{rv} = Voltage Rise Time, 10–90% V_{clamp}
t_{fi} = Current Fall Time, 90–10% I_C
t_{ti} = Current Tail, 10–2% I_C
t_c = Crossover Time, 10% V_{clamp} to 10% I_C

An enlarged portion of the turn–off waveforms is shown in Figure 7 to aid in the visual identity of these terms.

SWITCHING TIMES NOTE (continued)

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN–222:

$$P_{SWT} = 1/2 \; V_{CC} I_C (t_C) f$$

In general, $t_{rv} + t_{fi} \simeq t_C$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_C and t_{sv}) which are guaranteed at 100°C.

RESISTIVE SWITCHING PERFORMANCE
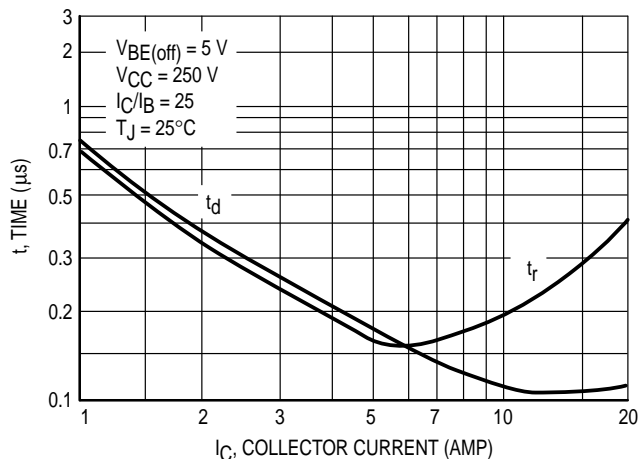
Figure 8. Turn–On Time
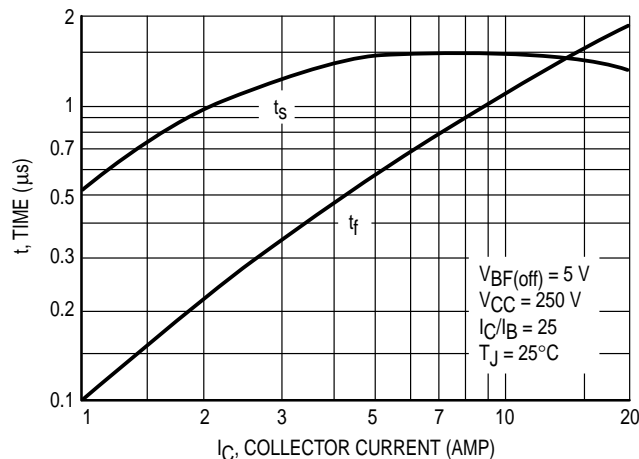
Figure 9. Turn–Off Time
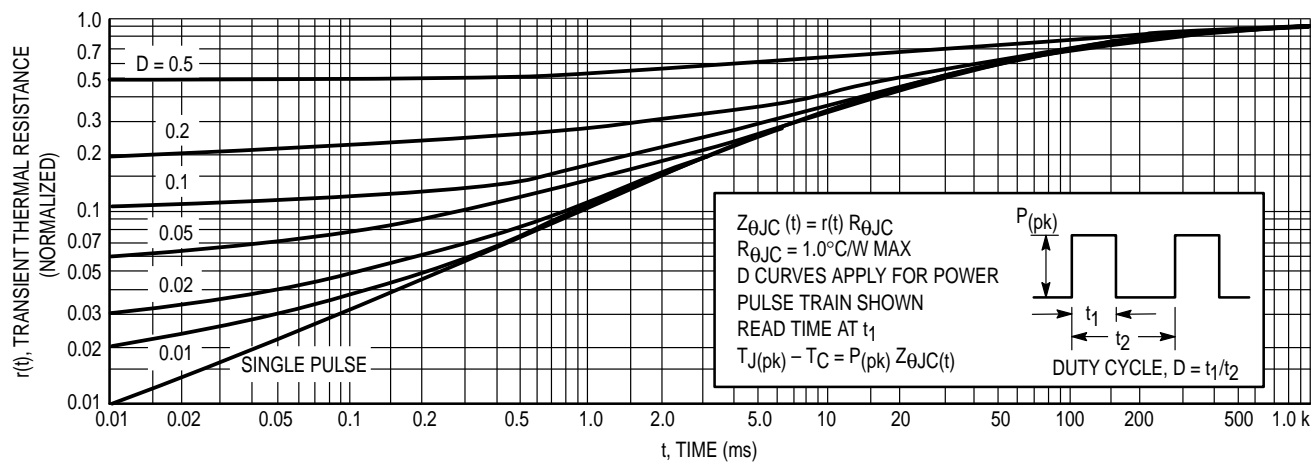
Figure 10. Thermal Response

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The Safe Operating Area figures shown in Figures 11 and 12 are specified for these devices under the test conditions shown.
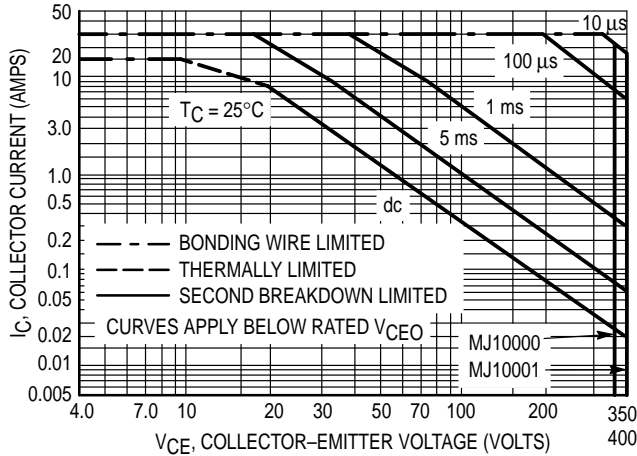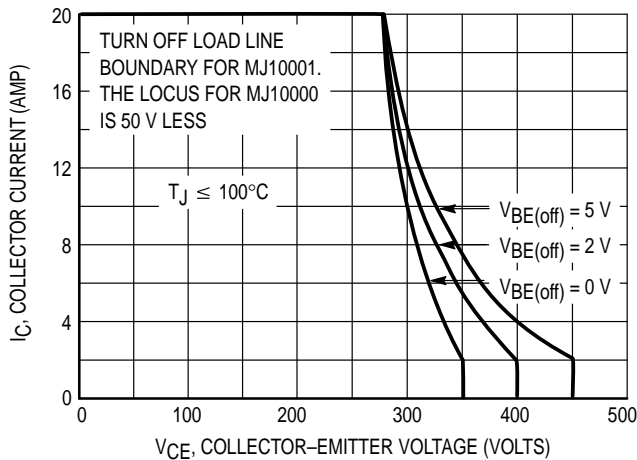

Figure 11. Forward Bias Safe Operating Area

**Figure 12. Reverse Bias Switching
Safe Operating Area**

SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second break-down. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipa-tion than the curves indicate.

The data of Figure 11 is based on $T_C = 25°C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \geq 25°C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 11 may be found at any case temperature by using the appropriate curve on Figure 13.

$T_{J(pk)}$ may be calculated from the data in Figure 10. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations im-posed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn–off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as $V_{CEX(sus)}$ at a given collector current and represents a voltage–current condition that can be sus-tained during reverse biased turn–off. This rating is verified under clamped conditions so that the device is never sub-jected to an avalanche mode. Figure 12 gives the complete reverse bias safe operating area characteristics.
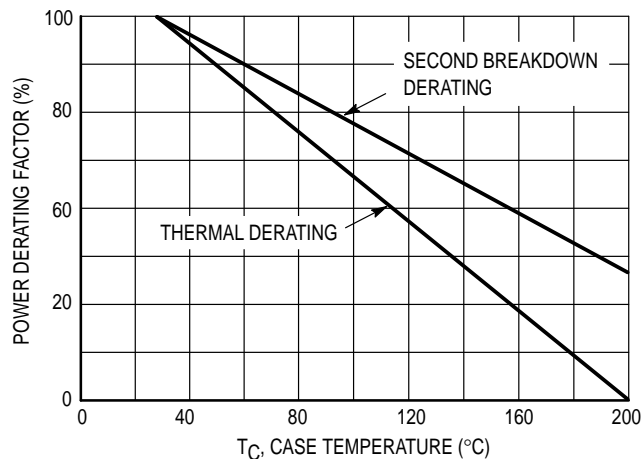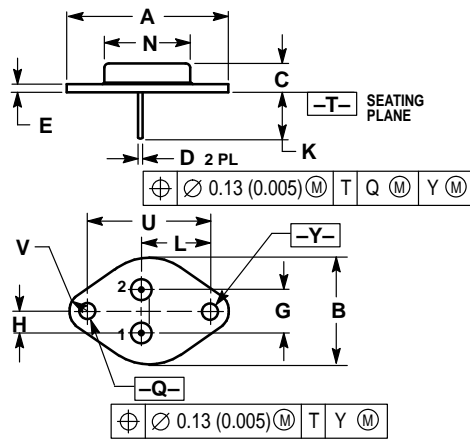

Figure 13. Power Derating

PACKAGE DIMENSIONS

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO–204AA OUTLINE SHALL APPLY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.550 REF		39.37 REF	
B	—	1.050	—	26.67
C	0.250	0.335	6.35	8.51
D	0.038	0.043	0.97	1.09
E	0.055	0.070	1.40	1.77
G	0.430 BSC		10.92 BSC	
H	0.215 BSC		5.46 BSC	
K	0.440	0.480	11.18	12.19
L	0.665 BSC		16.89 BSC	
N	—	0.830	—	21.08
Q	0.151	0.165	3.84	4.19
U	1.187 BSC		30.15 BSC	
V	0.131	0.188	3.33	4.77

STYLE 1:
  PIN 1. BASE
     2. EMITTER
  CASE: COLLECTOR

CASE 1–07
TO–204AA (TO–3)
ISSUE Z

MOTOROLA

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